IPC ASSOCIATION CON ELECTRONICS IND	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both lev	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier In	formation	,					,		,					
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi											2024-05-21			
Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
uthorized Re	epresentative*	Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
Rec	equester Item Number			Mfr Item Name		I	Effective Date	Version	Version Manufacturing Site		V	Veight*	UOM	Unit Type
				60V 1A Schottky R	0V 1A Schottky Rectif		2024-05-21 TSCBE		СВЕ	6.0		mg	Each	
Ianufactu i	ring Proccess Informa	ation												
Terminal Plating / Grid Array Material Ter			erminal Base Alloy J-STD-020 MSL Rat			ating	g Peak Process Body Temperature Max Time at Pea			Max Time at Peak	k Temperature Number of Reflow Cycles			
Mat	tte Tin (Sn) - annealed	C	CU Alloy	1			260	C		30	second	ls 3		
omments														
vel 1 - maxin	num time at peak temperat	ture during sol	dering is 10-3	30 seconds										
or more info	rmation regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier provides in this f											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.22	mg	Supplier	Iron (Fe)	7439-89-6		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.2196	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.68	mg	Supplier	Titanium (Ti)	7440-32-6		0.001	mg
			Supplier	Silver (Ag)	7440-22-4		0.0253	mg
			Supplier	Silicon (Si)	7440-21-3		0.6474	mg
			В	Nickel (Ni)	7440-02-0		0.0063	mg
Die Attach Solder	0.25	mg	Supplier	Silver (Ag)	7440-22-4		0.0063	mg
			A	Lead (Pb)	7439-92-1	7a	0.2313	mg
			Supplier	Tin (Sn)	7440-31-5		0.0125	mg
Lead Frame	1.39	mg	Supplier	Iron (Fe)	7439-89-6		0.0014	mg
			Supplier	Copper (Cu)	7440-50-8		1.3882	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0004	mg
Mold Compound-Black	3.26	mg		Metal Hydroxide	proprietary data		0.163	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0326	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.445	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.326	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2934	mg
Plating	0.2	mg	Supplier	Tin (Sn)	7440-31-5		0.2	mg